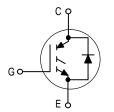
Product Preview Data Sheet

Insulated Gate Bipolar Transistor with Anti-Parallel Diode

N-Channel Enhancement Mode Silicon Gate

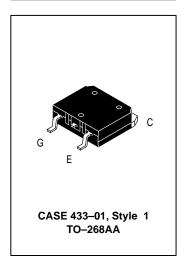
This Insulated Gate Bipolar Transistor (IGBT) is co-packaged with a soft recovery ultra-fast rectifier and uses an advanced termination scheme to provide an enhanced and reliable high voltage blocking capability. Short circuit rated IGBTs are specifically suited for applications requiring a guaranteed short circuit withstand time. Fast switching characteristics result in efficient operations at high frequencies. Co-packaged IGBTs save space, reduce assembly time and cost.

- High Power Surface Mount D3PAK Package
- High Speed E_{off}: 160 μJ/A typical at 125°C
- High Short Circuit Capability 10 μs minimum
- Soft Recovery Free Wheeling Diode is included in the package
- Robust High Voltage Termination



MGV12N120D

IGBT & DIODE IN D3PAK 12 A @ 90°C 20 A @ 25°C 1200 VOLTS SHORT CIRCUIT RATED



MAXIMUM RATINGS (T_{.1} = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCES	1200	Vdc
Collector–Gate Voltage ($R_{GE} = 1.0 \text{ M}\Omega$)	VCGR	1200	Vdc
Gate-Emitter Voltage — Continuous	VGE	±20	Vdc
Collector Current — Continuous @ T _C = 25°C — Continuous @ T _C = 90°C — Repetitive Pulsed Current (1)	I _{C25} I _{C90} I _{CM}	20 12 40	Adc Apk
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	123 0.98	Watts W/°C
Operating and Storage Junction Temperature Range	T _J , T _{Stg}	-55 to 150	°C
Short Circuit Withstand Time $(V_{CC} = 720 \text{ Vdc}, V_{GE} = 15 \text{ Vdc}, T_J = 125^{\circ}\text{C}, R_G = 20 \Omega)$	t _{SC}	10	μS
Thermal Resistance — Junction to Case – IGBT — Junction to Case – Diode — Junction to Ambient	R _θ JC R _θ JC R _θ JA	1.02 1.41 45	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C

⁽¹⁾ Pulse width is limited by maximum junction temperature.

This document contains information on a new product. Specifications and information are subject to change without notice.



MGV12N120D

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Cha	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS		•	•	•	•	•
Collector-to-Emitter Breakdown Vo (VGE = 0 Vdc, I _C = 250 μAdc) Temperature Coefficient (Positive	BVCES	1200 —	— 870	_	Vdc mV/°C	
Zero Gate Voltage Collector Current (VCE = 1200 Vdc, VGE = 0 Vdc) (VCE = 1200 Vdc, VGE = 0 Vdc, TJ = 125°C)		CES	_ _	_ _	100 2500	μAdc
Gate-Body Leakage Current (VGE = ± 20 Vdc, VCE = 0 Vdc)		IGES	_	_	250	nAdc
ON CHARACTERISTICS (1)						
Collector-to-Emitter On-State Voltage (VGE = 15 Vdc, I _C = 5 Adc) (VGE = 15 Vdc, I _C = 10 Adc, T _J = 125°C) (VGE = 15 Vdc, I _C = 10 Adc)		VCE(on)	 - -	2.51 2.36 3.21	3.37 — 4.42	Vdc
Gate Threshold Voltage (V _{CE} = V _{GE} , I _C = 1 mAdc) Threshold Temperature Coefficient (Negative)		VGE(th)	4.0 —	6.0 10	8.0 —	Vdc mV/°C
Forward Transconductance (V _{CE} = 10 Vdc, I _C = 10 Adc)		9fe	_	12	_	Mhos
DYNAMIC CHARACTERISTICS						
Input Capacitance		C _{ies}	-	930	-	pF
Output Capacitance	$(V_{CE} = 25 \text{ Vdc}, V_{GE} = 0 \text{ Vdc}, f = 1.0 \text{ MHz})$	C _{oes}	_	126	_]
Transfer Capacitance	,	C _{res}	-	16	-	1
SWITCHING CHARACTERISTICS (1)					
Turn-On Delay Time	(V _{CC} = 720 Vdc, I _C = 10 Adc,	^t d(on)	_	80	_	ns
Rise Time	$V_{GE} = 15 \text{ Vdc}, L = 300 \mu\text{H}$	t _r	_	114	_	
Turn-Off Delay Time	$R_G = 20 \Omega, T_J = 25^{\circ}C)$ Energy losses include "tail"	^t d(off)	_	66	_	
Fall Time	Energy losses include tall	t _f	-	232	-]
Turn-Off Switching Loss		E _{off}	-	0.57	1.33	mJ
Turn-On Switching Loss		Eon	_	1.12	1.88	1
Total Switching Loss		E _{ts}	_	1.69	3.21	1
Turn-On Delay Time	// 700 \/da - 40 Ada	td(on)	_	74	_	ns
Rise Time	$(V_{CC} = 720 \text{ Vdc}, I_{C} = 10 \text{ Adc}, V_{GE} = 15 \text{ Vdc}, L = 300 \mu\text{H}$	t _r	_	110	_	
Turn-Off Delay Time	$R_G = 20 \Omega$, $T_J = 125$ °C) Energy losses include "tail"	td(off)	_	80	_	
Fall Time	Energy losses include tall	t _f	_	616	_	1
Turn–Off Switching Loss		E _{off}	_	1.60	_	mJ
Turn-On Switching Loss		E _{on}	_	2.30	_	1
Total Switching Loss		E _{ts}	_	3.90	_	1
Gate Charge	(V _{CC} = 720 Vdc, I _C = 10 Adc, V _{GE} = 15 Vdc)	QT	_	31	_	nC
		Q ₁	_	13	_	1
		Q ₂	l –	14	_	1

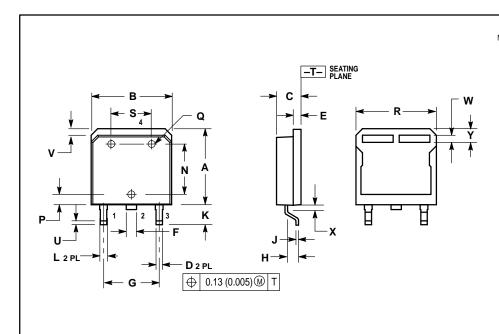
2 Motorola IGBT Device Data

Characteristic		Symbol	Min	Тур	Max	Unit	
DIODE CHARACTERISTICS							
Diode Forward Voltage Drop (IEC = 5 Adc) (IEC = 5 Adc, T _J = 125°C) (IEC = 10 Adc)		VFEC		2.75 2.50 3.50	3.22 — 4.18	Vdc	
Reverse Recovery Time		t _{rr}	-	54		ns	
	$(I_F = 10 \text{ Adc}, V_R = 720 \text{ Vdc},$	ta	1	30			
	dI _F /dt = 200 A/μs)	t _b	_	24	_		
Reverse Recovery Stored Charge		Q _{RR}	_	61	_	μC	
Reverse Recovery Time		t _{rr}	_	150		ns	
	$(I_F = 10 \text{ Adc}, V_R = 720 \text{ Vdc},$	t _a	_	102	_		
	$dI_F/dt = 200 \text{ A/}\mu\text{s}, T_J = 125^{\circ}\text{C}$	t _b	_	48			
Reverse Recovery Stored Charge		Q _{RR}	_	653	_	μC	

⁽¹⁾ Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

Motorola IGBT Device Data 3

PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.588	0.592	14.94	15.04	
В	0.623	0.627	15.82	15.93	
С	0.196	0.200	4.98	5.08	
D	0.048	0.052	1.22	1.32	
Е	0.058	0.062	1.47	1.57	
F	0.078	0.082	1.98	2.08	
G	0.430 BSC		1.092 BSC		
Н	0.105	0.110	2.67	2.79	
J	0.018	0.022	0.46	0.56	
K	0.150	0.160	3.81	4.06	
L	0.058	0.062	1.47	1.57	
N	0.353	0.357	8.97	9.07	
Р	0.078	0.082	1.98	2.08	
Q	0.053	0.057	1.35	1.45	
R	0.623	0.627	15.82	15.93	
S	0.313	0.317	7.95	8.05	
U	0.028	0.032	0.71	0.81	
٧	0.050		1.27	-	
W	0.054	0.058	1.37	1.47	
Х	0.050	0.060	1.27	1.52	
Υ	0.104	0.108	2.64	2.74	

STYLE 1:

PIN 1. BASE

2. COLLECTOR

3. EMITTER

4. COLLECTOR

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CASE 433-01

ISSUE B

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